

B. Claims

The following is a complete listing of the claims, and replaces all earlier versions and listings.

1. (Currently Amended) An electrode and wiring forming method, comprising:

a step of applying on a substrate a photosensitive resin containing a water-soluble photosensitive resin component and a water-soluble metallic compound;

a step of exposing the applied photosensitive resin;

a step of developing the exposed photosensitive resin to form on the substrate a base pattern containing at least the water-soluble metallic compound;

an absorbing step of absorbing an organic metallic compound ~~containing a metal different from that in the water-soluble metallic compound~~ into the base pattern; and

a baking step of baking the base pattern in which the organic metallic compound is absorbed at a temperature from 400°C to 600°C.

2. (Original) An electrode and wiring forming method according to claim 1, wherein a compounding ratio of the water-soluble metallic compound to the photosensitive resin component is 1.0 % by weight to 20 % by weight.

3. (Original) An electrode and wiring forming method according to claim 2, wherein the water-soluble metallic compound is a water-soluble metallic compound including rhodium, bismuth, ruthenium, vanadium, chromium, tin, lead, or silicon.

4. (Original) An electrode and wiring forming method according to claim 2, wherein the organic metallic compound is a complex and a ligand thereof is a nitrogen-containing compound.

5. (Original) An electrode and wiring forming method according to claim 4, wherein the nitrogen-containing compound is a nitrogen-containing compound having at most 8 carbon atoms.

6. (Original) An electrode and wiring forming method according to claim 2, wherein the organic metallic compound is a platinum complex.

7-10. (Cancelled)

11. (Currently Amended) A method of manufacturing an image-forming apparatus including a plurality of electron-emitting devices and an image-forming member for forming an image by irradiation of electron beams emitted from the electron-emitting devices, comprising:

forming said plurality of electron-emitting devices and said image-forming member,

wherein at least one of an electrode and a wiring is formed by the method comprising:

a step of applying on a substrate a photosensitive resin containing a water-soluble photosensitive resin component and a water-soluble metallic compound;

a step of exposing the applied photosensitive resin;

a step of developing the exposed photosensitive resin to form on the substrate a base pattern containing at least the water-soluble metallic compound;

an absorbing step of absorbing an organic metallic compound ~~containing a metal different from that in the water-soluble metallic compound~~ into the base pattern; and

a baking step of baking the base pattern in which the organic metallic compound is absorbed at a temperature from 400°C to 600°C.

12 (Currently Amended) An electroconductive member forming method, comprising:

a step of forming on a substrate a precursor pattern of the electroconductive member containing at least a metallic compound;

a step of absorbing an organic metallic compound ~~containing a metal different from that in the metallic compound~~ into the precursor pattern; and

a step of baking the precursor pattern that absorbed the organic metallic compound.

13. (Currently Amended) An electrode and wiring forming method, comprising:

a step of forming on a substrate a precursor pattern of the electrode and wiring containing at least a metallic compound;

a step of absorbing an organic metallic compound ~~containing a metal different from that in the metallic compound~~ into the precursor pattern; and

a step of baking the precursor pattern that absorbed the organic metallic compound.

14. (New) An electrode and wiring forming method according to claim 1, wherein the organic metallic compound contains a metal different from that in the water-soluble metallic compound.

15. (New) A method of manufacturing an image-forming apparatus according to claim 11, wherein the organic metallic compound contains a metal different from that in the water-soluble metallic compound.

16. (New) An electroconductive member forming method according to claim 12, wherein the organic metallic compound contains a metal different from that in the metallic compound.

17. (New) An electrode and wiring forming method according to claim 13, wherein the organic metallic compound contains a metal different from that in the metallic compound.